

ABSTRACT OF THE DISCLOSURE

A method of using blind via to house electronic components within an electrical device is provided. Such a method allows for the vertical orientation of various types of passive components within a layer of a printed circuit board (PCB) or an integrated passive device (IPD). One exemplary embodiment of the method provides for the passive component's electrical connection between an embedded ground and another device on the surface of the PCB. By virtue of its component positioning, such a method reduces the space demands placed upon the surface of the PCB, enhances the flexibility of circuitry design, and allows for a greater variety of passive components and integral passive devices to be utilized within the PCB itself. Another exemplary embodiment of the method provides for greater flexibility in the design and manufacture of IPDs by allowing for the vertical electrical connection of various passive components through the placement of intervening passive components into via.